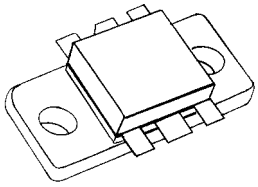
SGS-THOMSON MICROELECTRONICS

SD1650

RF & MICROWAVE TRANSISTORS CELLULAR BASE STATION APPLICATIONS

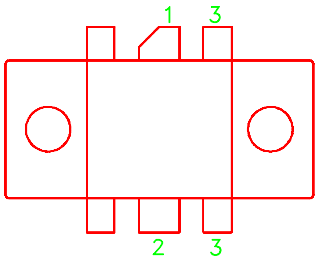
- REFRACTORY/GOLD METALLIZATION
- DOUBLE STEP INPUT/OUTPUT MATCH
- 850-960 MHz CLASS AB LINEAR
- COMMON EMITTER
- P_{OUT} = 60 W MIN. WITH 7 dB MIN GAIN



.400 6LFL (M169)
epoxy sealed

ORDER CODE	BRANDING
SD1650	SCELL500

PIN CONNECTION



1. Collector
2. Base
3. Emitter

DESCRIPTION

Designed for 900 MHz cellular radio base station applications, the SD1650 exhibits high collector efficiency with excellent thermal characteristics. Double-section internal input/output matching result in terminal impedance levels easily handled by the circuit designer.

ABSOLUTE MAXIMUM RATINGS (T_{case} = 25°C)

Symbol	Parameter	Value	Unit
V_{CBO}	Collector-Base Voltage	60	V
V_{CEO}	Collector-Emitter Voltage	28	V
V_{EBO}	Emitter-Base Voltage	4.0	V
I_C	Device Current	10	A
P_{DISS}	Power Dissipation (+25°C)	175	W
T_J	Junction Temperature	+200	°C
T_{STG}	Storage Temperature	– 65 to +150	°C

THERMAL DATA

$R_{TH(j-c)}$	Junction-Case Thermal Resistance	1.5	°C/W

*Applies only to rated RF amplifier operation

ELECTRICAL SPECIFICATIONS (T_{case} = 25°C)

STATIC

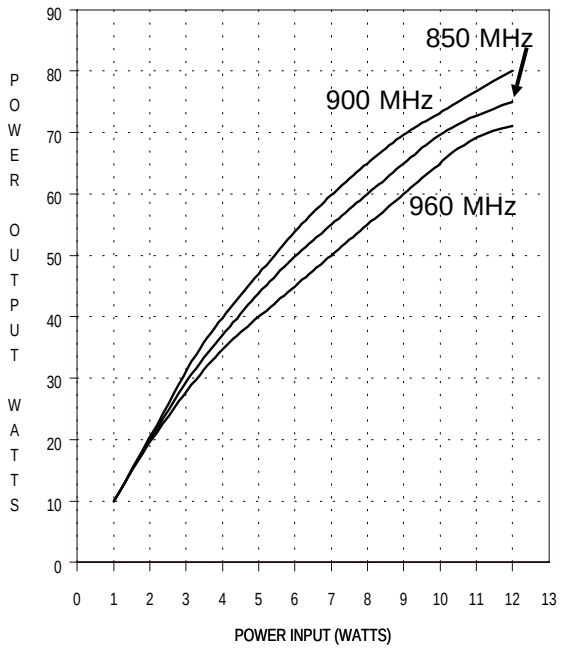
Symbol	Test Conditions	Value			Unit
		Min.	Typ.	Max.	
BV_{CBO}	I_C = 50mA	60	—	—	V
BV_{EBO}	I_E = 20mA	3.0	—	—	V
BV_{CES}	I_C = 100mA	60	—	—	V
BV_{CEO}	I_C = 100mA	28	—	—	V
I_{CEO}	V_{CE} = 24V	—	—	10	mA
h_{FE}	V_{CE} = 5V I_C = 6A	20	—	200	—

DYNAMIC

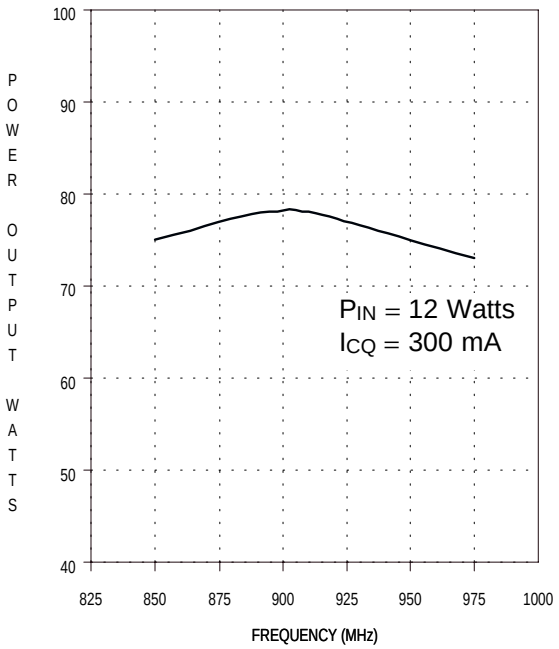
Symbol	Test Conditions			Value			Unit
				Min.	Typ.	Max.	
P_{OUT}	f = 900 MHz	P_{IN} = 12 W	I_{CQ} = 300 mA	60	—	—	W
ηc	f = 900 MHz	P_{IN} = 12 W	I_{CQ} = 300 mA	45	—	—	%
G_P	f = 900 MHz	P_{IN} = 12 W	I_{CQ} = 300 mA	7	—	—	dB
VSWR	f = 900 MHz	P_{IN} = 12 W		3:1	—	—	—

TYPICAL PERFORMANCE

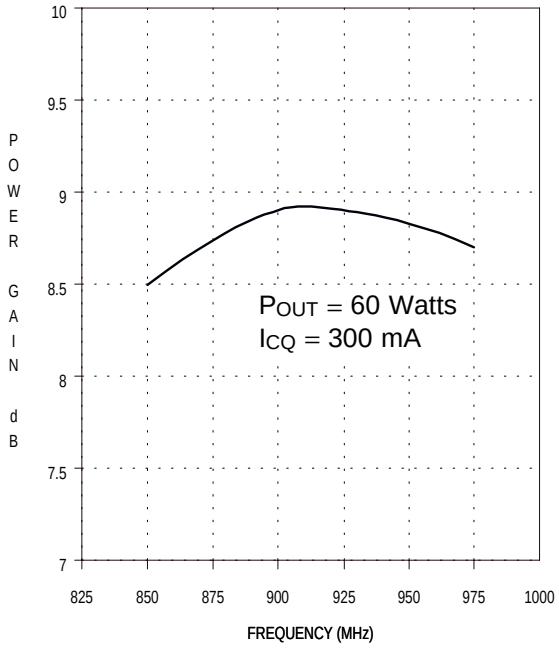
BROADBAND POWER OUTPUT vs POWER INPUT



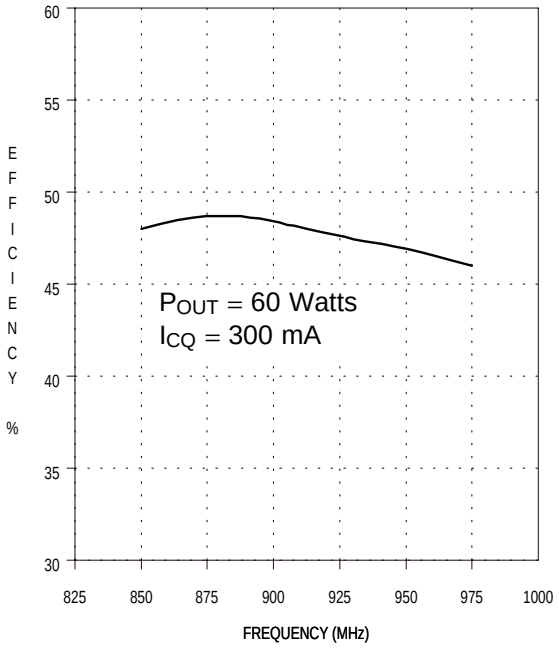
BROADBAND POWER OUTPUT vs FREQUENCY



BROADBAND POWER GAIN vs FREQUENCY



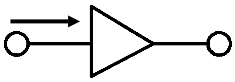
BROADBAND EFFICIENCY vs FREQUENCY



IMPEDANCE DATA

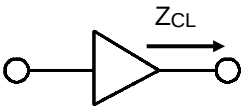
TYPICAL INPUT IMPEDANCE

Z_{IN}



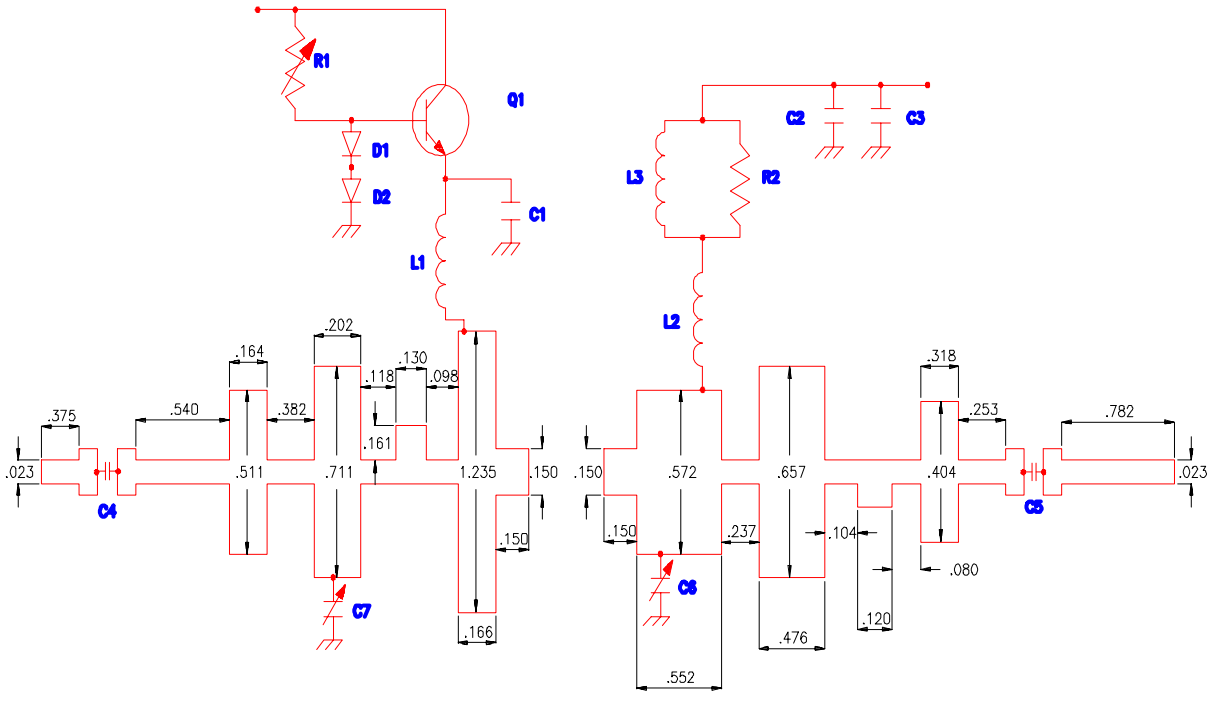
TYPICAL COLLECTOR LOAD IMPEDANCE

Z_{CL}



FREQ.	Z_{IN} (Ω)	Z_{CL} (Ω)
850 MHz	2.4 + j 5.2	4.0 – j 1.3
870 MHz	2.6 + j 5.4	3.9 – j 2.3
900 MHz	3.2 + j 6.3	3.6 – j 2.6
930 MHz	4.1 + j 6.0	3.4 – j 2.4
960 MHz	4.7 + j 5.6	3.0 – j 3.0

TEST CIRCUIT

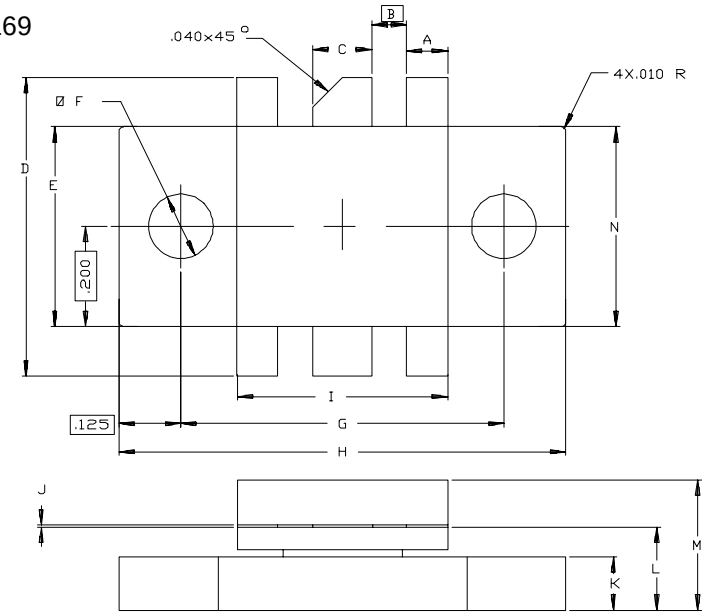


C1,C2 : 220 pF Chip Capacitor ATC Size B
C3 : 10 Microfarad Electrolytic Capacitor
C4,C5 : 220 pF Chip Capacitor ATC Size B
C6,C7 : 1 - 4 pF Johanson Variable Capacitor
D1,D2 : 1N3064 Diode or Equiv

L1,L2 : 5 Turn 1/4" Dia. 16 AWG Coil
Q1 : SD1438-02 or Equiv.
R1 : 5KΩ Potentiometer
R2 : 100Ω 1/4 Watt Resistor
Er =10.2 H =.025in.

PACKAGE MECHANICAL DATA

Ref. Dwg. No.: 12-0169



SGS-THOMSON MICROELECTRONICS		
	MINIMUM Inches/mm	MAXIMUM Inches/mm
A	.078/1,98	.088/2,24
B	.120/3,05	
C	.115/2,92	.125/3,18
D	.580/14,73	.620/15,75
E	.395/10,03	.405/10,29
F	.125/3,18	
G	.720/18,29	.730/18,54
H	.970/24,64	.980/24,89
I	.420/10,67	.430/10,92
J	.002/0,05	.007/0,18

CONT'D		
	MINIMUM Inches/mm	MAXIMUM Inches/mm
K	.105/2,67	.115/2,92
L	.159/4,04	.175/4,45
M		.280/7,11
N	.395/10,03	.408/10,36